

N-Channel Power MOSFET

100V, 70A, $13m\Omega$

FEATURES

- Low R_{DS(ON)} to minimize conductive loss
- Low gate charge for fast power switching
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

ΛD	DI	IC	ION

- Synchronous Rectifier in SMPS
- LED lighting application
- 48V Battery System

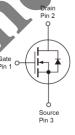
KEY PERFORMANCE PARAMETERS			
PARAMETER	VALUE	UNIT	
V _{DS}	100	V	
R _{DS(on)} (max)	13	mΩ	
Q _g	145	nC	











Notes: MSL 3 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER	70	SYMBOL	Limit	UNIT
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V_{GS}	±20	V
	$T_C = 25^{\circ}C$		70	
Continuous Drain Current (Note 3)	T _C = 70°C		61	A
Continuous Diain Current	$T_A = 25^{\circ}C$	I _D	12	A
	T _A = 70°C		9	
Drain Current-Pulsed (Note 1)	I _{DM}	150	А	
Avalanche Current, L=0.5mH	I _{AS} , I _{AR}	25	А	
Avalanche Energy, L=0.5mH		E _{AS} , E _{AR}	156	mJ
Ť	$T_C = 25^{\circ}C$		120	
Maximum Dawar Dissination (Note 2)	$T_C = 70$ °C		80	_ w
Maximum Power Dissipation (Note 2)	T _A = 25°C	I _D	8.3	VV
	T _A = 70°C		5.3	
Storage Temperature Range	T _{STG}	- 55 to +150	°C	
Operating Junction Temperature Range		T _J	- 55 to +150	°C



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	Limit	UNIT	
Thermal Resistance – Junction to Case	R _{eJC}	1	°C/W	
Thermal Resistance – Junction to Ambient	$R_{\Theta JA}$	40	°C/W	

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV _{DSS}	100	7	-	V
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 30A$	R _{DS(ON)}		10	13	mΩ
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	$V_{GS(TH)}$	2	3	4	V
Zero Gate Voltage Drain Current	$V_{DS} = 80V, V_{GS} = 0V$	I _{DSS}	(7	1	μΑ
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
Dynamic						
Total Gate Charge		Q_g)	145		
Gate-Source Charge	$V_{DS} = 50V, I_{D} = 30A,$	Q_{gs}		25		nC
Gate-Drain Charge	$V_{GS} = 10V$	Q_{gd}		43		
Input Capacitance		C _{iss}		4300		_
Output Capacitance	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1.0MHz	C _{oss}		300		pF
Reverse Transfer Capacitance	1 = 1.0IVIN2	C _{rss}		120		
Switching						
Turn-On Delay Time		t _{d(on)}		27		
Turn-On Rise Time	$V_{GS} = 10V$, $V_{DS} = 50V$, $R_G = 3\Omega$,	t _r		13		
Turn-Off Delay Time		t _{d(off)}		15		ns
Turn-Off Fall Time		t _f		42		
Source-Drain Diode						
Forward On Voltage	$V_{GS} = 0V, I_{S} = 30A$	V _{SD}		0.8	1.3	V
Reverse Recovery Time	I _S = 30A, T _J = 25°C	t _{rr}		165		ns
Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	Q _{rr}		175		nC

Notes:

- 1. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%
- 2. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4PCB in still air.

2

3. The maximum current is limited by package.



ORDERING INFORMATION

PART NO.	PACKAGE	PACKING	
TSM70N10CP ROG	TO-252 (DPAK)	2,500pcs / 13" Reel	
TSM70N10CH C5G	TO-251 (IPAK)	75pcs / Tube	
TSM70N10CH X0G	TO-251S (IPAK SL)	75pcs / Tube	

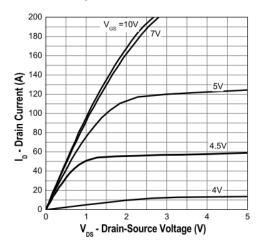




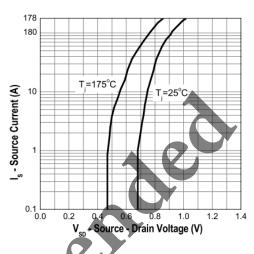
CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

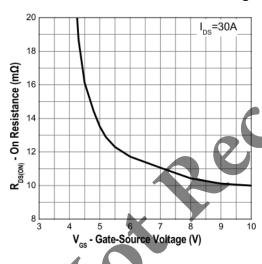
Output Characteristics



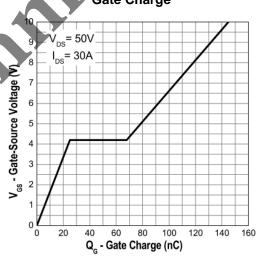
Transfer Characteristics



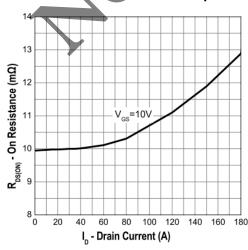
On-Resistance vs. Gate-Source Voltage



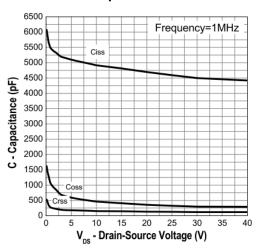
Gate Charge



On-Resistance vs. Junction Temperature



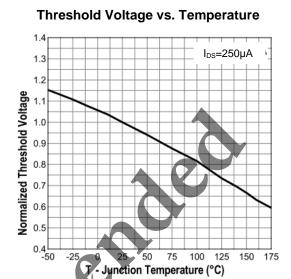
Capacitance



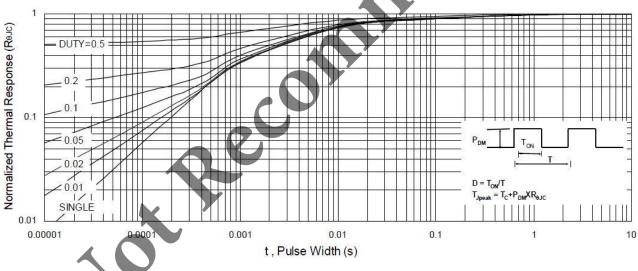


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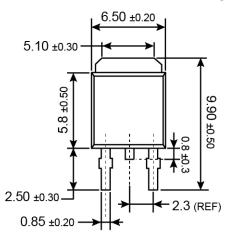
Normalized Thermal Transient Impedance, Junction-to-Ambient

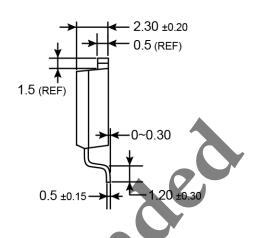




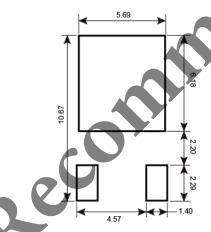
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



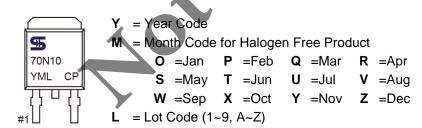




SUGGESTED PAD LAYOUT (Unit: Millimeters)



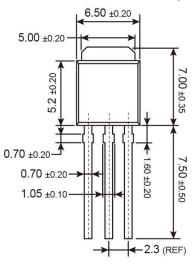
MARKING DIAGRAM

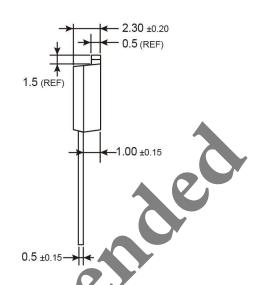




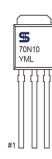
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)







MARKING DIAGRAM



Y = Year Code

M = Month Code for Halogen Free Product

O =Jan P =Feb Q =Mar

Jan Pereb Q = Iviai

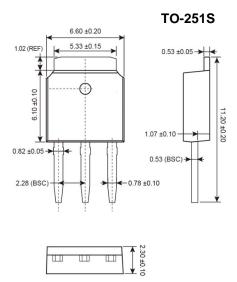
S =May T =Jun U =Jul V =Au

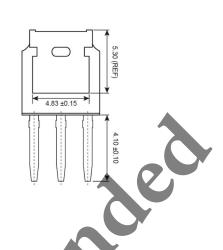
W = Sep X = Oct Y = Nov Z = Dec

L = Lot Code (1~9, A~Z)

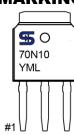


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